

# Assembly Bill of Materials

# Texas Instruments

Project Name:	PMP10666
Project File:	PMP10666_Project.PrjPcb
Base ID:	PMP10666
Schematic Rev:	E1
Assembly Variant:	None
Build Quantity:	100
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Item	Designator	Description	RoHS	Manufacturer	PartNumber	Quantity
1	!PCB1	Printed Circuit Board	O	Any	PMP10666	1
2	C1, C2	CAP, CERM, 2200pF, 2000V, +/-10%, X7R, 1812	Y	TDK	C4532X7R3D222K	2
3	C3	CAP, CERM, 100 µF, 6.3 V, +/- 20%, X5R, 1206	Y	Taiyo Yuden	JMK316BJ107ML-T	1
4	C4	CAP, CERM, 22 µF, 6.3 V, +/- 10%, X7R, 1206	Y	MuRata	GRM31CR70J226KE19L	1
5	C5	CAP, CERM, 0.47 µF, 6.3 V, +/- 10%, X7R, 0603	Y	Kemet	C0603C474K9RACTU	1
6	C6, C16	CAP, CERM, 0.22µF, 50V, +/-10%, X7R, 0805	Y	TDK	C2012X7R1H224K	2
7	C7, C8, C9	CAP, AL, 10 µF, 200 V, +/- 20%, TH	Y	Rubycon	200CFX10MEFC10X16	3
8	C10	CAP, CERM, 0.1 µF, 250 V, +/- 10%, X7R, 1812	Y	Kemet	C1812C104KARACTU	1
9	C11	CAP, CERM, 100pF, 250V, +/-5%, C0G/NP0, 0805	Y	MuRata	GRM21A5C2E101JW01D	1
10	C12	CAP, CERM, 100 pF, 25 V, +/- 10%, X7R, 0603	Y	AVX	06033C101KAT2A	1
11	C13	CAP, CERM, 0.01µF, 50V, +/-10%, X7R, 0603	Y	TDK	C1608X7R1H103K	1
12	C14	CAP, CERM, 1000 pF, 100 V, +/- 5%, X7R, 0603	Y	AVX	06031C102JAT2A	1
13	C15, C19	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0603	Y	AVX	06035C104KAT2A	2
14	C17	CAP, CERM, 0.47µF, 16V, +/-10%, X7R, 0805	Y	TDK	C2012X7R1C474K	1
15	C18	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	Y	TDK	C1608C0G1H101J	1
16	D1	Diode, Superfast Rectifier, 400 V, 1 A, SMA	Y	Diodes Inc.	ES1G-13-F	1
17	D2	Diode, Superfast Rectifier, 50 V, 3 A, SMB	Y	Diodes Inc.	ES3AB-13-F	1
18	D3	Diode, Zener, 20 V, 550 mW, SMB	Y	ON Semiconductor	1SMB5932BT3G	1
19	D4, D5	Diode, Switching, 75V, 0.15A, SOT-323	Y	Diodes Inc.	BAS16W-7-F	2
20	FID1, FID2, FID3	Fiducial mark. There is nothing to buy or mount.	Y	N/A	N/A	3
21	H1, H2, H3, H4	Machine Screw, Round, #4-40 x 1/4, Nylon, Philips panhead	Y	B&F Fastener Supply	NY PMS 440 0025 PH	4
22	H5, H6, H7, H8	Standoff, Hex, 0.5"L #4-40 Nylon	Y	Keystone	1902C	4
23	J1, J2, J3, J4	Standard Banana Jack, Uninsulated, 5.5mm	Y	Keystone	575-4	4
24	LBL1	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	Y	Brady	THT-14-423-10	1
25	Q1	MOSFET, N-CH, 40V, 15A, SON 5x6mm	Y	Texas Instruments	CSD18504Q5A	1
26	R1	RES, 931, 1%, 0.125 W, 0805	Y	Vishay-Dale	CRCW0805931RFKEA	1
27	R2	RES, 41.2 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW060341K2FKEA	1
28	R3	RES, 100, 5%, 0.75 W, 2010	Y	Vishay-Dale	CRCW2010100RJNEF	1
29	R4	RES, 4.7 ohm, 5%, 0.1W, 0603	Y	Vishay-Dale	CRCW06034R70JNEA	1
30	R5	RES, 45.3 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW060345K3FKEA	1
31	R6	RES, 1.30 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW06031K30FKEA	1
32	R7	RES, 33 k, 5%, 0.75 W, 2010	Y	Vishay-Dale	CRCW201033K0JNEF	1
33	R8	RES, 0 ohm, 5%, 0.1W, 0603	Y	Panasonic	ERJ-3GEY0R00V	1
34	R9	RES, 0.01, 1%, 1 W, 2010	Y	Stackpole Electronics Inc	CSRN2010FK10L0	1
35	R10	RES, 4.70 k, 1%, 0.1 W, 0603	Y	Yageo America	RC0603FR-074K7L	1
36	R11	RES, 10.0k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW060310K0FKEA	1
37	R12	RES, 5.62 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW06035K62FKEA	1
38	R13	RES, 162 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW0603162KFKEA	1
39	R14	RES, 1.00k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW06031K00FKEA	1
40	R15	RES, 5.62 k, 1%, 0.1 W, 0603	Y	Yageo America	RC0603FR-075K62L	1
41	R16	RES, 127 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW0603127KFKEA	1
42	R17	RES, 56.2 k, 1%, 0.1 W, 0603	Y	Vishay-Dale	CRCW060356K2FKEA	1
43	R18	RES, 2.74k ohm, 1%, 0.1W, 0603	Y	Vishay-Dale	CRCW06032K74FKEA	1
44	T1	Transformer, 1.5uH, SMT	Y	Würth Elektronik	750315626	1
45	U1	High Efficiency Low-Side N-Channel Controller for Switching Regulators, 10-pin MSOP	N	National Semiconductor	LM3481MM	1
46	U2	Optocoupler, 5 kV, 50-600% CTR, TH-4	Y	Lite-On	LTV-817S	1
47	U3	PRECISION PROGRAMMABLE REFERENCE, DBZ0003A	Y	Texas Instruments	TL431AIDBZ	1

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